

| Form PTO-1449 | | U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE | | ATTY. DOCKET NO. M122-2401 | | SERIAL NO. <i>10/784</i> Filed Herewith <i>074</i> | |
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| LIST OF ART CITED BY APPLICANT (Use several sheets if necessary) | | | | APPLICANT Micron Technology, Inc. | | | |
| | | | | FILING DATE Filed Herewith <i>20 FEB 01</i> | | GROUP Unknown <i>2823</i> | |
| U.S. PATENT DOCUMENTS | | | | | | | |
| Examiner Initial | Document Number | Date | Name | Class | Subclass | Filing Date if Appropriate | |
| <i>QNB</i> | AA | 6,107,109 | Akram et al. | <i>138</i> | <i>15</i> | X | |
| <i>QNB</i> | AB | 6,114,240 | Akram et al. | <i>434</i> | <i>667</i> | X | |
| <i>QNB</i> | AC | 6,294,837 | Akram et al. | <i>257</i> | <i>774</i> | X | |
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| | AK | | | | | | |
| | AL | | | | | | |
| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | |
| <i>QNB</i> | AM | <i>X</i> | Electroless Plating; http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm ; 12/5/2003; pp. 1-4 | | | | |
| <i>QNB</i> | AN | | Electroless Plating; http://www.corrosion-doctors.org/MetalCoatings/Electroless.htm ; 10/20/2003; pp. 1-2 | | | | |
| <i>QNB</i> | AO | | Slide Show: "Through-Wafer Copper Electroplating for RF Silicon Technology"; N.T. Nguyen et al.; DIMES - TU Delft, Netherlands; http://www.essderc2002.deis.unibo.it/ESSDERC_web/Session_D11/D11_2.pdf | | | | |
| <i>QNB</i> | AP | <i>X</i> | "Atomic Layer Deposition of TIN Films by Alternate Supply of Tetraalkylmethylamino-Titanium and Ammonia" : Jae-Sik Min, Young-Woong Son, et al.; Jpn. J. Appl. Phys. Vol. 37 (1998) pp. 4999-5004; Part 1, No. 9A; September 1998 Japanese Journal of Applied Physics | | | | |
| EXAMINER <i>William M. Brewster</i> | | | DATE CONSIDERED <i>26 Nov 04</i> | | | | |
| <small>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</small> | | | | | | | |

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| | AL | | | | | | |
| OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.) | | | | | | | |
| 97B | AM | X | *Kinetic modeling of film growth rates of TiN films in atomic layer deposition*, Jung-Wook Lim et al.' Journal of Applied Physics; Vol. 87, No. 9; 1 May 2000; pp. 4632-4634 | | | | |
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| EXAMINER <u>William M. Brown</u> | | | | DATE CONSIDERED <u>26 Nov 01</u> | | | |
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